



Material Content Data Sheet



Sales Product Name		IPL65R165CFD		Issued		27. September 2017		
MA#		MA001139114						
Package		PG-VSON-4-1		Weight*		192.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.566	6.00	6.00	59983	59983
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		66	
	non noble metal	zinc	7440-66-6	0.051	0.03		264	
	non noble metal	iron	7439-89-6	1.017	0.53		5275	
wire	non noble metal	copper	7440-50-8	41.300	21.42	21.99	214200	219805
	non noble metal	copper	7440-50-8	1.717	0.89	0.89	8907	8907
	encapsulation	organic material	carbon black	1333-86-4	0.204	0.11		1058
	plastics	epoxy resin	-	10.502	5.45		54465	
	inorganic material	silicondioxide	60676-86-0	91.251	47.31	52.87	473263	528786
leadfinish	non noble metal	tin	7440-31-5	2.397	1.24	1.24	12434	12434
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1307	1307
solder	noble metal	silver	7440-22-4	0.187	0.10		971	
	non noble metal	tin	7440-31-5	0.150	0.08		776	
	non noble metal	lead	7439-92-1	7.149	3.71	3.89	37077	38824
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		39	
	non noble metal	zinc	7440-66-6	0.030	0.02		156	
	non noble metal	iron	7439-89-6	0.601	0.31		3119	
	non noble metal	copper	7440-50-8	24.418	12.66	12.99	126640	129954
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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